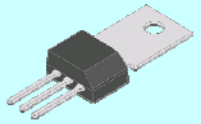
FAGOR
Fagor Electrónica, S. Coop.

# MATERIAL COMPOSITION DECLARATION

**Date: 09.02.2007**

## Supplier: Fagor Electrónica S. Coop



**Package: TO202-1**

**Part Number:** **Description: SCR's and Triacs**

| COMPOSITION PART | MATERIAL NAME | MATERIAL MASS( mg) | MATERIAL MASS( %) | ELEMENT NAME COMPOSITION | CAS Nº | ELEMENT % ( BY WEIGHT) | Cd (ppm) | Pb (ppm) | Hg (ppm) | Cr 6+ (ppm) | PBBs (ppm) | PBDEs (ppm) |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| LEAD FRAME | Cu alloy | 228,400 | 16,81% | Cu<br>Fe<br>P | 7440-508<br>7439-896<br>7723-140 | 99,87<br>0,1<br>0,03 | <5 | 12 | <5 | <5 | <5 | <5 |
| ENCAPSULATION | Epoxy | 1049,100 | 77,21% | Fused silica<br>Polyglycidiyl Ether O-cresol Formaldehyde Novolac<br>Brominated Epoxy resin<br>Antimony oxide<br>Carbon black | 60676-86-0<br>29690-82-2<br><br>40039-93-8<br>1309-64-4<br>1333-86-4 | 70-75<br>10-15<br><br>1-3<br>1-3<br>1-3 | <5 | 12 | <5 | <5 | <5 | <5 |
| CHIP | Doped Silicon<br>Glass Passivated | 1,780 | 0,13% | Si<br>Al<br>Ni<br>SiO2<br>PbO<br>Al2O3 | 7440-213<br>7429-90-5<br>7440-02-0<br>7631-86-9<br>1317-36-8<br>1344-28-1 | 88,7-90,1<br>0,9-1,3<br>0,8-1,2<br>4,1-4,3<br>3,8-4<br>0,3-0,5 | < 1 | < 10<br><br><br><br>36200<br>(**) | < 0,5 | < 10 | < 200 | < 200 |
| DIE BONDING MATERIAL | Solder Wire | 3,340 | 0,25% | Pb<br>Sn<br>Ag | 7489-92-1<br>7440-31-5<br>7440-22-4 | 95<br>2,5<br>2,5 | <5 | 950000<br>(*) | <5 | <5 | <5 | <5 |
| WIRES | Aluminum | 0,870 | 0,06% | Al | 7429-90-5 | 100 | <5 | 12 | <5 | <5 | <5 | <5 |
| COATING | Sn | 75,310 | 5,54% | Sn | 7440-31-5 | 100 | <5 | 12 | <5 | <5 | <5 | <5 |
| WHOLE ITEM | | **1358,800** | 100,00% | | | | | | | | | |

**Exception according to annex of Directive 2002/95/EC (RoHS):**

* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

** Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes

MONDRAGON COMPONENTES